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Features

- Core
 - ARM® Cortex®-M3 revision 2.0 running at up to 64 MHz
 - Memory Protection Unit (MPU)
 - Thumb[®]-2 instruction set
- Pin-to-pin compatible with AT91SAM7S legacy products (48- and 64-pin versions)
- Memories
 - From 64 to 256 Kbytes embedded Flash, 128-bit wide access, memory accelerator, single plane
 - From 16 to 48 Kbytes embedded SRAM
 - 16 Kbytes ROM with embedded bootloader routines (UART, USB) and IAP routines
 - 8-bit Static Memory Controller (SMC): SRAM, PSRAM, NOR and NAND Flash support
 - Memory Protection Unit (MPU)
- System
 - Embedded voltage regulator for single supply operation
 - Power-on-Reset (POR), Brown-out Detector (BOD) and Watchdog for safe operation
 - Quartz or ceramic resonator oscillators: 3 to 20 MHz main power with Failure
 Detection and optional low power 32.768 kHz for RTC or device clock
 - High precision 8/12 MHz factory trimmed internal RC oscillator with 4 MHz default frequency for device startup. In-application trimming access for frequency adjustment
 - Slow Clock Internal RC oscillator as permanent low-power mode device clock
 - Two PLLs up to 130 MHz for device clock and for USB
 - Temperature Sensor
 - Up to 22 peripheral DMA (PDC) channels
- Low Power Modes
 - Sleep and Backup modes, down to 3 µA in Backup mode
 - Ultra low power RTC
- Peripherals
 - USB 2.0 Device: 12 Mbps, 2668 byte FIFO, up to 8 bidirectional Endpoints. On-Chip Transceiver
 - Up to 2 USARTs with ISO7816, IrDA®, RS-485, SPI, Manchester and Modem Mode
 - Two 2-wire UARTs
 - Up to 2 Two Wire Interface (I2C compatible), 1 SPI, 1 Serial Synchronous Controller (I2S), 1 High Speed Multimedia Card Interface (SDIO/SD Card/MMC)
 - Up to 6 Three-Channel 16-bit Timer/Counter with capture, waveform, compare and PWM mode. Quadrature Decoder Logic and 2-bit Gray Up/Down Counter for Stepper Motor
 - 4-channel 16-bit PWM with Complementary Output, Fault Input, 12-bit Dead Time Generator Counter for Motor Control
 - 32-bit Real-time Timer and RTC with calendar and alarm features
 - Up to 15-channel, 1Msps ADC with differential input mode and programmable gain stage
 - One 2-channel 12-bit 1Msps DAC
 - One Analog Comparator with flexible input selection, Selectable input hysteresis
 - 32-bit Cyclic Redundancy Check Calculation Unit (CRCCU)
- I/O
 - Up to 79 I/O lines with external interrupt capability (edge or level sensitivity), debouncing, glitch filtering and on-die Series Resistor Termination
 - Three 32-bit Parallel Input/Output Controllers, Peripheral DMA assisted Parallel Capture Mode
- Packages
 - 100-lead LQFP, 14 x 14 mm, pitch 0.5 mm/100-ball LFBGA, 9 x 9 mm, pitch 0.8 mm
 - 64-lead LQFP, 10 x 10 mm, pitch 0.5 mm/64-pad QFN 9x9 mm, pitch 0.5 mm
 - 48-lead LQFP, 7 x 7 mm, pitch 0.5 mm/48-pad QFN 7x7 mm, pitch 0.5 mm



AT91SAM ARM-based Flash MCU

SAM3S Series

Summary

NOTE: This is a summary document. The complete document is available on the Atmel website at www.atmel.com.







1. SAM3S Description

Atmel's SAM3S series is a member of a family of Flash microcontrollers based on the high performance 32-bit ARM Cortex-M3 RISC processor. It operates at a maximum speed of 64 MHz and features up to 256 Kbytes of Flash and up to 48 Kbytes of SRAM. The peripheral set includes a Full Speed USB Device port with embedded transceiver, a High Speed MCI for SDIO/SD/MMC, an External Bus Interface featuring a Static Memory Controller providing connection to SRAM, PSRAM, NOR Flash, LCD Module and NAND Flash, 2x USARTs, 2x UARTs, 2x TWIs, 3x SPI, an I2S, as well as 1 PWM timer, 6x general-purpose 16-bit timers, an RTC, an ADC, a 12-bit DAC and an analog comparator.

The SAM3S series is ready for capacitive touch thanks to the QTouch library, offering an easy way to implement buttons, wheels and sliders

The SAM3S device is a medium range general purpose microcontroller with the best ratio in terms of reduced power consumption, processing power and peripheral set. This enables the SAM3S to sustain a wide range of applications including consumer, industrial control, and PC peripherals.

It operates from 1.62V to 3.6V and is available in 48-, 64- and 100-pin QFP, 48- and 64-pin QFN, and 100-pin BGA packages.

The SAM3S series is the ideal migration path from the SAM7S series for applications that require more performance. The SAM3S series is pin-to-pin compatible with the SAM7Sseries.

1.1 Configuration Summary

The SAM3S series devices differ in memory size, package and features list. Table 1-1 below summarizes the configurations of the device family

Table 1-1. Configuration Summary

Device	Flash	SRAM	Timer Counter Channels	GPIOs	UART/ USARTs	ADC	12-bit DAC Output	External Bus Interface	HSMCI	Package
SAM3S4C	256 Kbytes single plane	48 Kbytes	6	79	2/2 ⁽¹⁾	16 ch.	2	8-bit data, 4 chip selects, 24-bit address	1 port 4 bits	LQFP100 BGA100
SAM3S4B	256 Kbytes single plane	48 Kbytes	3	47	2/2	10 ch.	2	-	1 port 4 bits	LQFP64 QFN 64
SAM3S4A	256 Kbytes single plane	48 Kbytes	3	34	2/1	8 ch.	-	-	-	LQFP48 QFN 48
SAM3S2C	128 Kbytes single plane	32 Kbytes	6	79	2/2 ⁽¹⁾	16 ch.	2	8-bit data, 4 chip selects, 24-bit address	1 port 4 bits	LQFP100 BGA100
SAM3S2B	128 Kbytes single plane	32 Kbytes	3	47	2/2	10 ch.	2	-	1 port 4 bits	LQFP64 QFN 64
SAM3S2A	128 Kbytes single plane	32 Kbytes	3	34	2/1	8 ch.	-	-	-	LQFP48 QFN 48
SAM3S1C	64 Kbytes single plane	16 Kbytes	6	79	2/2 ⁽¹⁾	16 ch.	2	8-bit data, 4 chip selects, 24-bit address	1 port 4 bits	LQFP100 BGA100
SAM3S1B	64 Kbytes single plane	16 Kbytes	3	47	2/2	10 ch.	2	-	1 port 4 bits	LQFP64 QFN 64
SAM3S1A	64 Kbytes single plane	16 Kbytes	3	34	2/1	8 ch.	-	-	-	LQFP48 QFN 48

Note: 1. Full Modem support on USART1.

2. SAM3S Block Diagram

Figure 2-1. SAM3S 100-pin Version Block Diagram

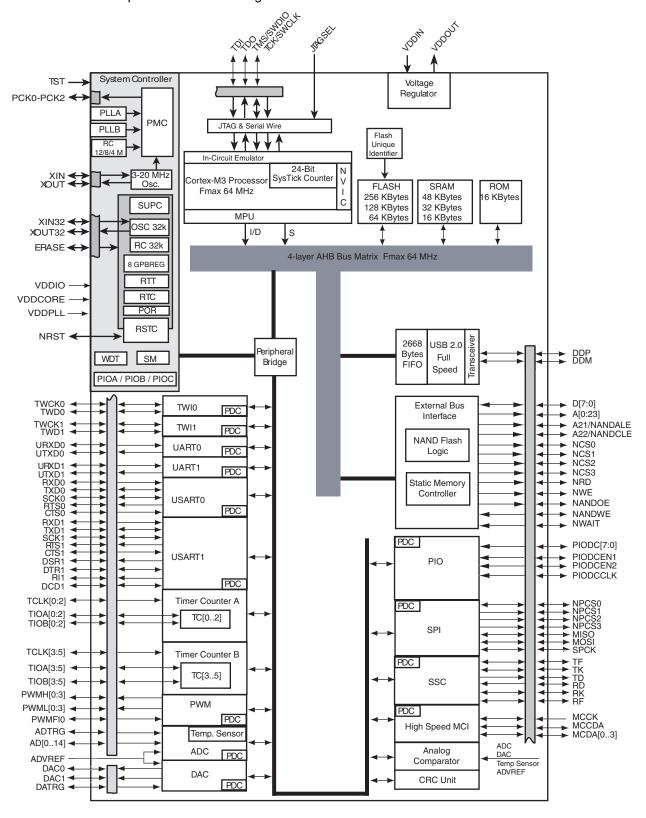






Figure 2-2. SAM3S 64-pin Version Block Diagram

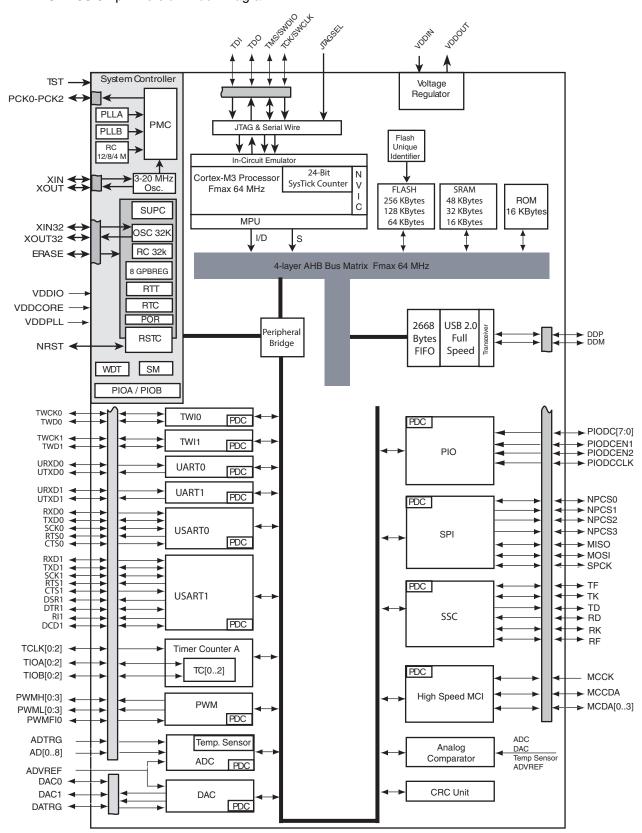
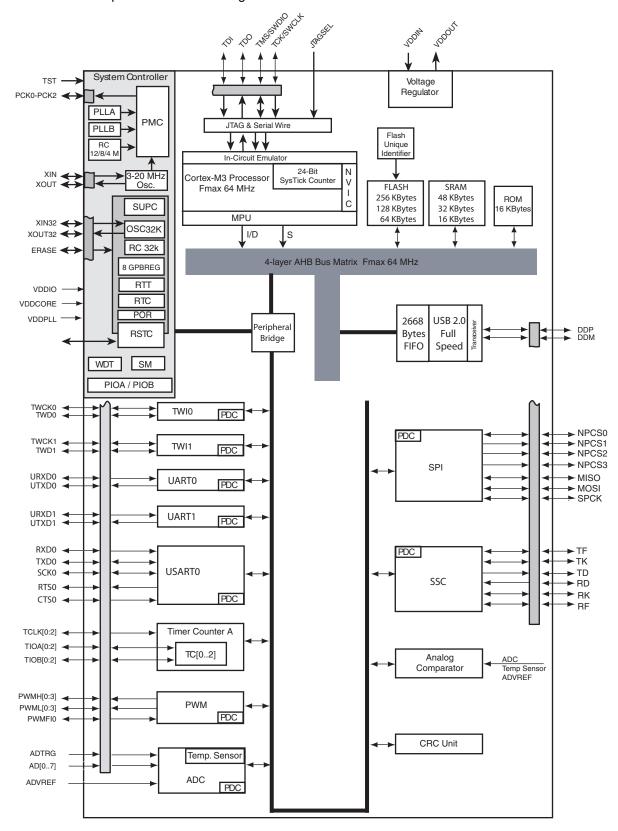


Figure 2-3. SAM3S 48-pin Version Block Diagram







3. Signal Description

Table 3-1 gives details on the signal names classified by peripheral.

 Table 3-1.
 Signal Description List

Signal Name	Function	Туре	Active Level	Voltage reference	Comments
-	Power S	Supplies		1	
VDDIO	Peripherals I/O Lines and USB transceiver Power Supply	Power			1.62V to 3.6V
VDDIN	Voltage Regulator Input, ADC, DAC and Analog Comparator Power Supply	Power			1.8V to 3.6V ⁽⁴⁾
VDDOUT	Voltage Regulator Output	Power			1.8V Output
VDDPLL	Oscillator and PLL Power Supply	Power			1.62 V to 1.95V
VDDCORE	Power the core, the embedded memories and the peripherals	Power			1.62V to 1.95V
GND	Ground	Ground			
	Clocks, Oscilla	ators and PLI	_S		
XIN	Main Oscillator Input	Input			Reset State:
XOUT	Main Oscillator Output	Output			- PIO Input
XIN32	Slow Clock Oscillator Input	Input			- Internal Pull-up disabled
XOUT32	Slow Clock Oscillator Output	Output		VDDIO	- Schmitt Trigger enabled ⁽¹⁾
PCK0 - PCK2	Programmable Clock Output	Output			Reset State: - PIO Input - Internal Pull-up enabled - Schmitt Trigger enabled ⁽¹⁾
	Serial Wire/JTAG De	ebug Port - S	WJ-DP		
TCK/SWCLK	Test Clock/Serial Wire Clock	Input			
TDI	Test Data In	Input			Reset State: - SWJ-DP Mode
TDO/TRACESWO	Test Data Out / Trace Asynchronous Data Out	Output		VDDIO	- Internal pull-up disabled - Schmitt Trigger enabled ⁽¹⁾
TMS/SWDIO	Test Mode Select /Serial Wire Input/Output	Input / I/O			Committe magger emabled
JTAGSEL	JTAG Selection	Input	High		Permanent Internal pull-down
	Flash M	lemory			
ERASE	Flash and NVM Configuration Bits Erase Command	Input	High	VDDIO	Reset State: - Erase Input - Internal pull-down enabled - Schmitt Trigger enabled ⁽¹⁾
	Rese	t/Test			
NRST	Synchronous Microcontroller Reset		Low	VDDIO	Permanent Internal pull-up
TST	Test Select	Input			Permanent Internal pull-down

 Table 3-1.
 Signal Description List (Continued)

Signal Name	Function	Туре	Active Level	Voltage reference	Comments
	Universal Asynchronou	s Receiver Trans	smitter - U	ARTx	
URXDx	UART Receive Data	Input			
UTXDx	UART Transmit Data	Output			
	PIO Controlle	r - PIOA - PIOB -	PIOC		
PA0 - PA31	Parallel IO Controller A	I/O			Reset State:
PB0 - PB14	Parallel IO Controller B	I/O		VDDIO	- PIO or System IOs ⁽²⁾
PC0 - PC31	Parallel IO Controller C	I/O		- Internal pull-up enal - Schmitt Trigger enal	
	PIO Controller - Paral	lel Capture Mod	e (PIOA Or	nly)	
PIODC0-PIODC7	Parallel Capture Mode Data	Input			
PIODCCLK	Parallel Capture Mode Clock	Input		VDDIO	
PIODCEN1-2	Parallel Capture Mode Enable	Input		-	
	Externa	I Bus Interface	1	1	
D0 - D7	Data Bus	I/O			
A0 - A23	Address Bus	Output			
NWAIT	External Wait Signal	Input	Low		
	Static Memo	ory Controller - S	SMC	1	
NCS0 - NCS3	Chip Select Lines	Output	Low		
NRD	Read Signal	Output	Low		
NWE	Write Enable	Output	Low		
	NANI) Flash Logic		1	
NANDOE	NAND Flash Output Enable	Output	Low		
NANDWE	NAND Flash Write Enable	Output	Low		
	High Speed Multime	edia Card Interfa	ice - HSMC		
MCCK	Multimedia Card Clock	I/O			
MCCDA	Multimedia Card Slot A Command	I/O			
MCDA0 - MCDA3	Multimedia Card Slot A Data	I/O			
	Universal Synchronous Async	hronous Receive	er Transmi	tter USARTx	[
SCKx	USARTx Serial Clock	I/O			
TXDx	USARTx Transmit Data	I/O			
RXDx	USARTx Receive Data	Input			
RTSx	USARTx Request To Send	Output			
CTSx	USARTx Clear To Send	Input			
DTR1	USART1 Data Terminal Ready	I/O			
DSR1	USART1 Data Set Ready	Input			
DCD1	USART1 Data Carrier Detect	Input			
RI1	USART1 Ring Indicator	Input			





 Table 3-1.
 Signal Description List (Continued)

Signal Name	Function	Туре	Active Level	Voltage reference	Comments
	Synchronous Seri	al Controller	- SSC		
TD	SSC Transmit Data	Output			
RD	SSC Receive Data	Input			
TK	SSC Transmit Clock	I/O			
RK	SSC Receive Clock	I/O			
TF	SSC Transmit Frame Sync	I/O			
RF	SSC Receive Frame Sync	I/O			
	Timer/Co	unter - TC			
TCLKx	TC Channel x External Clock Input	Input			
TIOAx	TC Channel x I/O Line A	I/O			
TIOBx	TC Channel x I/O Line B	I/O			
	Pulse Width Modulat	on Controlle	r- PWMC	1	
PWMHx	PWM Waveform Output High for channel x	Output			
PWMLx	PWM Waveform Output Low for channel x	Output			only output in complementary mode when dead time insertion is enabled
PWMFI0	PWM Fault Input	Input			
	Serial Periphera	al Interface -	SPI		
MISO	Master In Slave Out	I/O			
MOSI	Master Out Slave In	I/O			
SPCK	SPI Serial Clock	I/O			
SPI_NPCS0	SPI Peripheral Chip Select 0	I/O	Low		
SPI_NPCS1 - SPI_NPCS3	SPI Peripheral Chip Select	Output	Low		
	Two-Wire In	terface- TWI			
TWDx	TWIx Two-wire Serial Data	I/O			
TWCKx	TWIx Two-wire Serial Clock	I/O			
	Ana	alog			
ADVREF	ADC, DAC and Analog Comparator Reference	Analog			
	Analog-to-Digital	Converter -	ADC		
AD0 - AD14	Analog Inputs	Analog, Digital			
ADTRG	ADC Trigger	Input		VDDIO	
	12-bit Digital-to-Ana	log Converte	er - DAC		
DAC0 - DAC1	Analog output	Analog, Digital			
DACTRG	DAC Trigger	Input		VDDIO	
	•				t .

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Туре	Active Level	Voltage reference	Comments	
	Fast Flash Programm	ning Interfac	e - FFPI			
PGMEN0-PGMEN2	Programming Enabling	Input		VDDIO		
PGMM0-PGMM3	Programming Mode	Input				
PGMD0-PGMD15	PGMD0-PGMD15 Programming Data I/O					
PGMRDY	Programming Ready	Output	High			
PGMNVALID	Data Direction	Output	Low	VDDIO		
PGMNOE	Programming Read	Input	Low			
PGMCK	Programming Clock	Input				
PGMNCMD	Programming Command	Input	Low			
	USB Full Speed Device					
DDM	USB Full Speed Data -	Analog			Reset State:	
DDP	USB Full Speed Data +	Analog, Digital		VDDIO	- USB Mode - Internal Pull-down ⁽³⁾	

- Notes: 1. Schmitt Triggers can be disabled through PIO registers.
 - 2. Some PIO lines are shared with System IOs.
 - 3. Refer to the USB sub section in the product Electrical Characteristics Section for Pull-down value in USB Mode.
 - 4. See Section 5.3 "Typical Powering Schematics" for restriction on voltage range of Analog Cells.





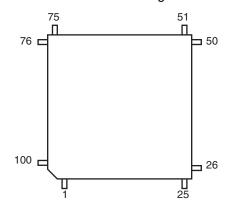
4. Package and Pinout

4.1 SAM3S4/2/1C Package and Pinout

Figure 4-2 shows the orientation of the 100-ball LFBGA Package

4.1.1 100-lead LQFP Package Outline

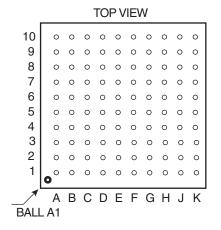
Figure 4-1. Orientation of the 100-lead LQFP Package



4.1.2 100-ball LFBGA Package Outline

The 100-Ball LFBGA package has a 0.8 mm ball pitch and respects Green Standards. Its dimensions are 9 x 9 x 1.1 mm.

Figure 4-2. Orientation of the 100-BALL LFBGA Package



4.1.3 100-Lead LQFP Pinout

Table 4-1. 100-lead LQFP SAM3S4/2/1C Pinout

1	ADVREF
2	GND
3	PB0/AD4
4	PC29/AD13
5	PB1/AD5
6	PC30/AD14
7	PB2/AD6
8	PC31
9	PB3/AD7
10	VDDIN
11	VDDOUT
12	PA17/PGMD5/AD0
13	PC26
14	PA18/PGMD6/AD1
15	PA21/PGMD9/AD8
16	VDDCORE
17	PC27
18	PA19/PGMD7/AD2
19	PC15/AD11
20	PA22/PGMD10/AD9
21	PC13/AD10
22	PA23/PGMD1
23	PC12/AD12
24	PA20/PGMD8/AD3
25	PC0

77 (17100 -172) 1 0 1 1110 dt				
26	GND			
27	VDDIO			
28	PA16/PGMD4			
29	PC7			
30	PA15/PGMD3			
31	PA14/PGMD2			
32	PC6			
33	PA13/PGMD1			
34	PA24/PGMD12			
35	PC5			
36	VDDCORE			
37	PC4			
38	PA25/PGMD13			
39	PA26/PGMD14			
40	PC3			
41	PA12/PGMD0			
42	PA11/PGMM3			
43	PC2			
44	PA10/PGMM2			
45	GND			
46	PA9/PGMM1			
47	PC1			
48	PA8/XOUT32/ PGMM0			
49	PA7/XIN32/ PGMNVALID			
50	VDDIO			

51	TDI/PB4
52	PA6/PGMNOE
53	PA5/PGMRDY
54	PC28
55	PA4/PGMNCMD
56	VDDCORE
57	PA27/PGMD15
58	PC8
59	PA28
60	NRST
61	TST
62	PC9
63	PA29
64	PA30
65	PC10
66	PA3
67	PA2/PGMEN2
68	PC11
69	VDDIO
70	GND
71	PC14
72	PA1/PGMEN1
73	PC16
74	PA0/PGMEN0
75	PC17

76	TDO/TRACESWO/PB 5
77	JTAGSEL
78	PC18
79	TMS/SWDIO/PB6
80	PC19
81	PA31
82	PC20
83	TCK/SWCLK/PB7
84	PC21
85	VDDCORE
86	PC22
87	ERASE/PB12
88	DDM/PB10
89	DDP/PB11
90	PC23
91	VDDIO
92	PC24
93	PB13/DAC0
94	PC25
95	GND
96	PB8/XOUT
97	PB9/PGMCK/XIN
98	VDDIO
99	PB14/DAC1
100	VDDPLL





4.1.4 100-ball LFBGA Pinout

Table 4-2.100-ball LFBGA SAM3S4/2/1C Pinout

A1	PB1/AD5
A2	PC29
А3	VDDIO
A4	PB9/PGMCK/XIN
A 5	PB8/XOUT
A6	PB13/DAC0
A7	DDP/PB11
A8	DDM/PB10
A9	TMS/SWDIO/PB6
A10	JTAGSEL
B1	PC30
B2	ADVREF
В3	GNDANA
B4	PB14/DAC1
B5	PC21
B6	PC20
B7	PA31
B8	PC19
B9	PC18
B10	TDO/TRACESWO/ PB5
C1	PB2/AD6
C2	VDDPLL
СЗ	PC25
C4	PC23
C5	ERASE/PB12

C6	TCK/SWCLK/PB7
C7	PC16
C8	PA1/PGMEN1
C9	PC17
C10	PA0/PGMEN0
D1	PB3/AD7
D2	PB0/AD4
D3	PC24
D4	PC22
D5	GND
D6	GND
D7	VDDCORE
D8	PA2/PGMEN2
D9	PC11
D10	PC14
E1	PA17/PGMD5/AD0
E2	PC31
E3	VDDIN
E4	GND
E5	GND
E6	NRST
E7	PA29/AD13
E8	PA30/AD14
E9	PC10
E10	PA3

F1	PA18/PGMD6/AD1
F2	PC26
F3	VDDOUT
F4	GND
F5	VDDIO
F6	PA27/PGMD15
F7	PC8
F8	PA28
F9	TST
F10	PC9
G1	PA21/PGMD9/AD8
G2	PC27
G3	PA15/PGMD3
G4	VDDCORE
G5	VDDCORE
G6	PA26/PGMD14
G7	PA12/PGMD0
G8	PC28
G9	PA4/PGMNCMD
G10	PA5/PGMRDY
H1	PA19/PGMD7/AD2
H2	PA23/PGMD11
НЗ	PC7
H4	PA14/PGMD2
H5	PA13/PGMD1

H6	PC4	
H7	PA11/PGMM3	
Н8	PC1	
H9	PA6/PGMNOE	
H10	TDI/PB4	
J1	PC15/AD11	
J2	PC0	
J3	PA16/PGMD4	
J4	PC6	
J5	PA24/PGMD12	
J6	PA25/PGMD13	
J7	PA10/PGMM2	
J8	GND	
J9	VDDCORE	
J10	VDDIO	
K1	PA22/PGMD10/AD9	
K2	PC13/AD10	
K3	PC12/AD12	
K4	PA20/PGMD8/AD3	
K 5	PC5	
K6	PC3	
K7	PC2	
K8	PA9/PGMM1	
K9	PA8/XOUT32/PGMM0	
K10	PA7/XIN32/ PGMNVALID	

4.2 SAM3S4/2/1B Package and Pinout

Figure 4-3. Orientation of the 64-pad QFN Package

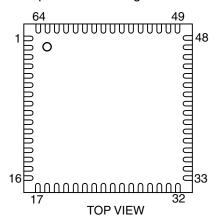
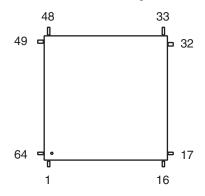


Figure 4-4. Orientation of the 64-lead LQFP Package







4.2.1 64-Lead LQFP and QFN Pinout

64-pin version SAM3S devices are pin-to-pin compatible with AT91SAM7S legacy products. Furthermore, SAM3S products have new functionalities shown in italic in Table 4-3.

Table 4-3. 64-pin SAM3S4/2/1B Pinout

1	ADVREF	17	GND	33	TDI/PB4	49	TDO/TRACESWO/PB5	
2	GND	18	VDDIO	34	PA6/PGMNOE	50	JTAGSEL	
3	PB0/AD4	19	PA16/PGMD4	35	PA5/PGMRDY	51	TMS/SWDIO/PB6	
4	PB1/AD5	20	PA15/PGMD3	36	PA4/PGMNCMD	52	PA31	
5	PB2/AD6	21	PA14/PGMD2	37	PA27/PGMD15	53	TCK/SWCLK/PB7	
6	PB3/AD7	22	PA13/PGMD1	38	PA28	54	VDDCORE	
7	VDDIN	23	PA24/PGMD12	39	NRST	55	ERASE/PB12	
8	VDDOUT	24	VDDCORE	40	TST	56	DDM/PB10	
9	PA17/PGMD5/ AD <i>0</i>	25	PA25/PGMD13	41	PA29	57	DDP/PB11	
10	PA18/PGMD6/ AD1	26	PA26/PGMD14	42	PA30	58	VDDIO	
11	PA21/PGMD9/ AD8	27	PA12/PGMD0	43	PA3	59	PB13/DAC0	
12	VDDCORE	28	PA11/PGMM3	44	PA2/PGMEN2	60	GND	
13	PA19/PGMD7/ AD2	29	PA10/PGMM2	45	VDDIO	61	XOUT/PB8	
14	PA22/PGMD10/ AD9	30	PA9/PGMM1	46	GND	62	XIN/PGMCK/PB9	
15	PA23/PGMD11	31	PA8/ <i>XOUT32/</i> PGMM0	47	PA1/PGMEN1	63	PB14/DAC1	
16	PA20/PGMD8/ AD3	32	PA7/ <i>XIN32/</i> PGMNVALID	48	PA0/PGMEN0	64	VDDPLL	
Notor	T		and must be sennested to		· · · · · · · · · · · · · · · · · · ·			

Note: The bottom pad of the QFN package must be connected to ground.

4.3 SAM3S4/2/1A Package and Pinout

Figure 4-5. Orientation of the 48-pad QFN Package

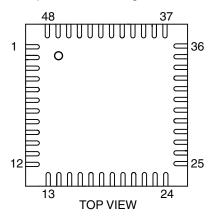
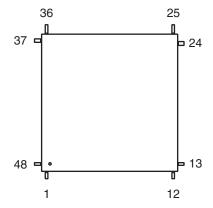


Figure 4-6. Orientation of the 48-lead LQFP Package





4.3.1 48-Lead LQFP and QFN Pinout

Table 4-4. 48-pin SAM3S4/2/1A Pinout

Iable	4-4. 40-pin SAM	1334	_
1	ADVREF		1
2	GND		1
3	PB0/AD4		1
4	PB1/AD5		1
5	PB2/AD6		1
6	PB3/AD7		1
7	VDDIN		1
8	VDDOUT		2
9	PA17/PGMD5/ AD0		2
10	PA18/PGMD6/ AD1		2
11	PA19/PGMD7/ AD2		2
12	PA20/AD3		2

13 VDDIO 14 PA16/PGMD4 15 PA15/PGMD3 16 PA14/PGMD2 17 PA13/PGMD1 18 VDDCORE 19 PA12/PGMD0 20 PA11/PGMM3 21 PA10/PGMM2 22 PA9/PGMM1 23 PA8/XOUT32/PGMM0					
15 PA15/PGMD3 16 PA14/PGMD2 17 PA13/PGMD1 18 VDDCORE 19 PA12/PGMD0 20 PA11/PGMM3 21 PA10/PGMM2 22 PA9/PGMM1 23 PA8/XOUT32/	13	VDDIO			
16 PA14/PGMD2 17 PA13/PGMD1 18 VDDCORE 19 PA12/PGMD0 20 PA11/PGMM3 21 PA10/PGMM2 22 PA9/PGMM1 23 PA8/XOUT32/	14	PA16/PGMD4			
17 PA13/PGMD1 18 VDDCORE 19 PA12/PGMD0 20 PA11/PGMM3 21 PA10/PGMM2 22 PA9/PGMM1 23 PA8/XOUT32/	15	PA15/PGMD3			
18 VDDCORE 19 PA12/PGMD0 20 PA11/PGMM3 21 PA10/PGMM2 22 PA9/PGMM1 PA8/XOUT32/	16	PA14/PGMD2			
19 PA12/PGMD0 20 PA11/PGMM3 21 PA10/PGMM2 22 PA9/PGMM1 23 PA8/XOUT32/	17	PA13/PGMD1			
20 PA11/PGMM3 21 PA10/PGMM2 22 PA9/PGMM1 23 PA8/XOUT32/	18	VDDCORE			
21 PA10/PGMM2 22 PA9/PGMM1 PA8/XOUT32/	19	PA12/PGMD0			
22 PA9/PGMM1 PA8/XOUT32/	20	PA11/PGMM3			
PA8/XOUT32/	21	PA10/PGMM2			
23	22	PA9/PGMM1			
	23	PA8/XOUT32/			
	23	PGMM0			
PA7/XIN32/	24	PA7/ <i>XIN32</i> /			
PGMNVALID	4 7	PGMNVALID			

25	TDI/PB4			
26	PA6/PGMNOE			
27	PA5/PGMRDY			
28	PA4/PGMNCMD			
29	NRST			
30	TST			
31	PA3			
32	PA2/PGMEN2			
33	VDDIO			
34	GND			
35	PA1/PGMEN1			
36	PA0/PGMEN0			

37	TDO/TRACESWO/ PB5			
38	JTAGSEL			
39	TMS/SWDIO/PB6			
40	TCK/SWCLK/PB7			
41	VDDCORE			
42	ERASE/PB12			
43	DDM/PB10			
44	DDP/PB11			
45	XOUT/PB8			
46	XIN/PB9/PGMCK			
47	VDDIO			
48	VDDPLL			

Note: The bottom pad of the QFN package must be connected to ground.

5. Power Considerations

5.1 Power Supplies

The SAM3S product has several types of power supply pins:

- VDDCORE pins: Power the core, the embedded memories and the peripherals; voltage ranges from 1.62V and 1.95V.
- VDDIO pins: Power the Peripherals I/O lines (Input/Output Buffers); USB transceiver; Backup part, 32kHz crystal oscillator and oscillator pads; ranges from 1.62V and 3.6V
- VDDIN pin: Voltage Regulator Input, ADC, DAC and Analog Comparator Power Supply;
 Voltage ranges from 1.8V to 3.6V
- VDDPLL pin: Powers the PLLA, PLLB, the Fast RC and the 3 to 20 MHz oscillator; voltage ranges from 1.62V and 1.95V.

5.2 Voltage Regulator

The SAM3S embeds a voltage regulator that is managed by the Supply Controller.

This internal regulator is intended to supply the internal core of SAM3S. It features two different operating modes:

- In Normal mode, the voltage regulator consumes less than 700 μA static current and draws 80 mA of output current. Internal adaptive biasing adjusts the regulator quiescent current depending on the required load current. In Wait Mode quiescent current is only 7 μA.
- In Backup mode, the voltage regulator consumes less than 1 μ A while its output (VDDOUT) is driven internally to GND. The default output voltage is 1.80V and the start-up time to reach Normal mode is inferior to 100 μ s.

For adequate input and output power supply decoupling/bypassing, refer to the Voltage Regulator section in the Electrical Characteristics section of the datasheet.

5.3 Typical Powering Schematics

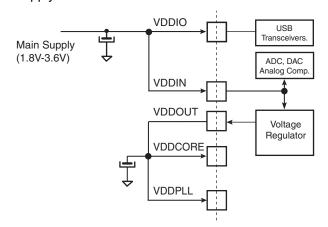
The SAM3S supports a 1.62V-3.6V single supply mode. The internal regulator input connected to the source and its output feeds VDDCORE. Figure 5-1 shows the power schematics.

As VDDIN powers the voltage regulator, the ADC/DAC and the analog comparator, when the user does not want to use the embedded voltage regulator, it can be disabled by software via the SUPC (note that it is different from Backup mode).





Figure 5-1. Single Supply

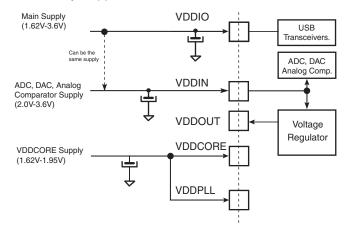


Note: Restrictions

With Main Supply < 2.0 V, USB and ADC/DAC and Analog comparator are not usable.

With Main Supply \geq 2.0V and < 3V, USB is not usable. With Main Supply \geq 3V, all peripherals are usable.

Figure 5-2. Core Externally Supplied



Note: Restrictions

With Main Supply < 2.0V, USB is not usable.

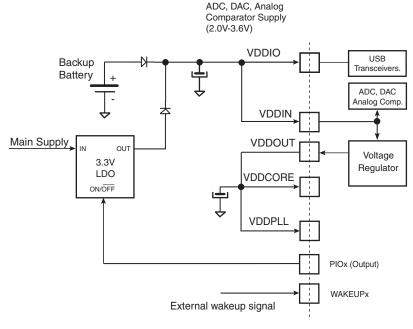
With VDDIN < 2.0V, ADC/DAC and Analog comparator are not usable.

With Main Supply \geq 2.0V and < 3V, USB is not usable.

With Main Supply and VDDIN ≥ 3V, all peripherals are usable.

Figure 5-3 below provides an example of the powering scheme when using a backup battery. Since the PIO state is preserved when in backup mode, any free PIO line can be used to switch off the external regulator by driving the PIO line at low level (PIO is input, pull-up enabled after backup reset). External wake-up of the system can be from a push button or any signal. See Section 5.6 "Wake-up Sources" for further details.

Figure 5-3. Backup Battery



Note: The two diodes provide a "switchover circuit" (for illustration purpose; between the backup battery and the main supply when the system is put in backup mode.

5.4 Active Mode

Active mode is the normal running mode with the core clock running from the fast RC oscillator, the main crystal oscillator or the PLLA. The power management controller can be used to adapt the frequency and to disable the peripheral clocks.

5.5 Low Power Modes

The various low power modes of the SAM3S are described below:

5.5.1 Backup Mode

The purpose of backup mode is to achieve the lowest power consumption possible in a system which is performing periodic wake-ups to perform tasks but not requiring fast startup time (<0.1ms). Total current consumption is 3 µA typical.

The Supply Controller, zero-power power-on reset, RTT, RTC, Backup registers and 32 kHz oscillator (RC or crystal oscillator selected by software in the Supply Controller) are running. The regulator and the core supply are off.

Backup mode is based on the Cortex-M3 deepsleep mode with the voltage regulator disabled.

The SAM3S can be awakened from this mode through WUP0-15 pins, the supply monitor (SM), the RTT or RTC wake-up event.

Backup mode is entered by using WFE instructions with the SLEEPDEEP bit in the System Control Register of the Cortex-M3 set to 1. (See the Power management description in The ARM Cortex M3 Processor section of the product datasheet).

Exit from Backup mode happens if one of the following enable wake up events occurs:





- WKUPEN0-15 pins (level transition, configurable debouncing)
- Supply Monitor alarm
- RTC alarm
- RTT alarm

5.5.2 Wait Mode

The purpose of the wait mode is to achieve very low power consumption while maintaining the whole device in a powered state for a startup time of less than 10 μ s. Current Consumption in Wait mode is typically 15 μ A (total current consumption) if the internal voltage regulator is used or 8 μ A if an external regulator is used.

In this mode, the clocks of the core, peripherals and memories are stopped. However, the core, peripherals and memories power supplies are still powered. From this mode, a fast start up is available.

This mode is entered via Wait for Event (WFE) instructions with LPM = 1 (Low Power Mode bit in PMC_FSMR). The Cortex-M3 is able to handle external events or internal events in order to wake-up the core (WFE). This is done by configuring the external lines WUP0-15 as fast startup wake-up pins (refer to Section 5.7 "Fast Startup"). RTC or RTT Alarm and USB wake-up events can be used to wake up the CPU (exit from WFE).

Entering Wait Mode:

- Select the 4/8/12 MHz fast RC oscillator as Main Clock
- Set the LPM bit in the PMC Fast Startup Mode Register (PMC_FSMR)
- Execute the Wait-For-Event (WFE) instruction of the processor

Note: Internal Main clock resynchronization cycles are necessary between the writing of MOSCRCEN bit and the effective entry in Wait mode. Depending on the user application, Waiting for MOSCRCEN bit to be cleared is recommended to ensure that the core will not execute undesired instructions.

5.5.3 Sleep Mode

The purpose of sleep mode is to optimize power consumption of the device versus response time. In this mode, only the core clock is stopped. The peripheral clocks can be enabled. The current consumption in this mode is application dependent.

This mode is entered via Wait for Interrupt (WFI) or Wait for Event (WFE) instructions with LPM = 0 in PMC FSMR.

The processor can be woke up from an interrupt if WFI instruction of the Cortex M3 is used, or from an event if the WFE instruction is used to enter this mode.

5.5.4 **Low Power Mode Summary Table**

The modes detailed above are the main low power modes. Each part can be set to on or off separately and wake up sources can be individually configured. Table 5-1 below shows a summary of the configurations of the low power modes.

Table 5-1. Low Power Mode Configuration Summary

Mode	SUPC, 32 kHz Oscillator RTC RTT Backup Registers, POR (Backup Region)	Regulator	Core Memory Peripherals	Mode Entry	Potential Wake Up Sources	Core at Wake Up	PIO State while in Low Power Mode	PIO State at Wake Up	Consumption (2) (3)	Wake-up Time ⁽¹⁾
Backup Mode	ON	OFF	OFF (Not powered)	WFE +SLEEPDEEP bit = 1	WUP0-15 pins SM alarm RTC alarm RTT alarm	Reset	Previous state saved	PIOA & PIOB & PIOC Inputs with pull ups	3 μA typ ⁽⁴⁾	< 0.1 ms
Wait Mode	ON	ON	Powered (Not clocked)	WFE +SLEEPDEEP bit = 0 +LPM bit = 1	I	Clocked back	Previous state saved	Unchanged	5 μΑ/15 μΑ ⁽⁵⁾	< 10 μs
Sleep Mode	ON	ON	Powered ⁽⁷⁾ (Not clocked)	WFE or WFI +SLEEPDEEP bit = 0 +LPM bit = 0	trom: Fact ctart-lin	Clocked back	Previous state saved	Unchanged	(6)	(6)

- Notes: 1. When considering wake-up time, the time required to start the PLL is not taken into account. Once started, the device works with the 4/8/12 MHz fast RC oscillator. The user has to add the PLL start-up time if it is needed in the system. The wake-up time is defined as the time taken for wake up until the first instruction is fetched.
 - 2. The external loads on PIOs are not taken into account in the calculation.
 - 3. Supply Monitor current consumption is not included.
 - 4. Total Current consumption.
 - 5. 5 μA on VDDCORE, 15 μA for total current consumption (using internal voltage regulator), 8 μA for total current consumption (without using internal voltage regulator).
 - 6. Depends on MCK frequency.
 - 7. In this mode the core is supplied and not clocked but some peripherals can be clocked.

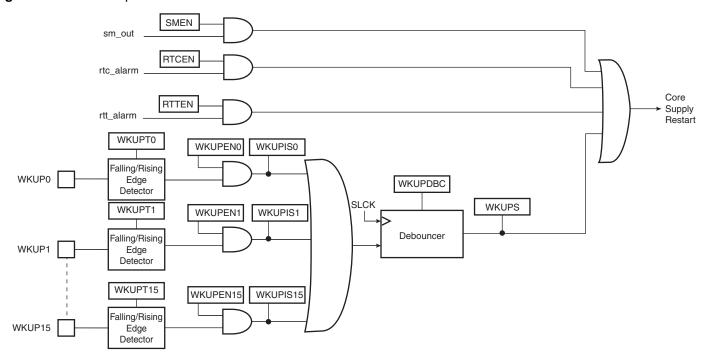




5.6 Wake-up Sources

The wake-up events allow the device to exit the backup mode. When a wake-up event is detected, the Supply Controller performs a sequence which automatically reenables the core power supply and the SRAM power supply, if they are not already enabled.

Figure 5-4. Wake-up Source

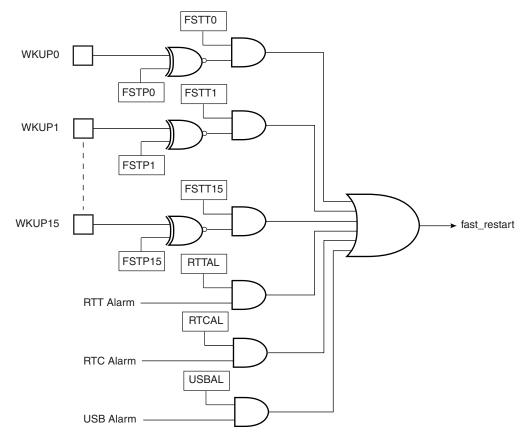


5.7 Fast Startup

The device allows the processor to restart in a few microseconds while the processor is in wait mode. A fast start up can occur upon detection of a low level on one of the 19 wake-up inputs (WKUP0 to 15 + SM + RTC + RTT).

The fast restart circuitry, as shown in Figure 5-5, is fully asynchronous and provides a fast start-up signal to the Power Management Controller. As soon as the fast start-up signal is asserted, the PMC automatically restarts the embedded 4/8/12 MHz fast RC oscillator, switches the master clock on this 4MHz clock and reenables the processor clock.

Figure 5-5. Fast Start-Up Circuitry







6. Input/Output Lines

The SAM3S has several kinds of input/output (I/O) lines such as general purpose I/Os (GPIO) and system I/Os. GPIOs can have alternate functionality due to multiplexing capabilities of the PIO controllers. The same PIO line can be used whether in IO mode or by the multiplexed peripheral. System I/Os include pins such as test pins, oscillators, erase or analog inputs.

6.1 General Purpose I/O Lines

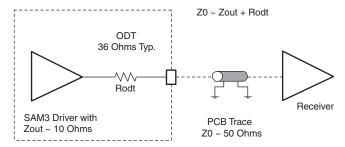
GPIO Lines are managed by PIO Controllers. All I/Os have several input or output modes such as pull-up or pull-down, input Schmitt triggers, multi-drive (open-drain), glitch filters, debouncing or input change interrupt. Programming of these modes is performed independently for each I/O line through the PIO controller user interface. For more details, refer to the product PIO controller section.

The input output buffers of the PIO lines are supplied through VDDIO power supply rail.

The SAM3S embeds high speed pads able to handle up to 32 MHz for HSMCI (MCK/2), 45 MHz for SPI clock lines and 35 MHz on other lines. See AC Characteristics Section in the Electrical Characteristics Section of the datasheet for more details. Typical pull-up and pull-down value is 100 k Ω for all I/Os.

Each I/O line also embeds an ODT (On-Die Termination), see Figure 6-1. It consists of an internal series resistor termination scheme for impedance matching between the driver output (SAM3S) and the PCB trace impedance preventing signal reflection. The series resistor helps to reduce IOs switching current (di/dt) thereby reducing in turn, EMI. It also decreases overshoot and undershoot (ringing) due to inductance of interconnect between devices or between boards. In conclusion ODT helps diminish signal integrity issues.

Figure 6-1. On-Die Termination



6.2 System I/O Lines

System I/O lines are pins used by oscillators, test mode, reset and JTAG to name but a few. Described below are the SAM3S system I/O lines shared with PIO lines:

These pins are software configurable as general purpose I/O or system pins. At startup the default function of these pins is always used.

Table 6-1. System I/O Configuration Pin List.

SYSTEM_IO bit number	Default function after reset	Other function	Constraints for normal start	Configuration
12	ERASE	PB12	Low Level at startup ⁽¹⁾	
10	DDM	PB10	-	
11	DDP	PB11	-	In Matrix User Interface Registers
7	TCK/SWCLK	PB7	-	(Refer to the SystemIO Configuration Register in the Bus Matrix section of
6	TMS/SWDIO	PB6	-	the product datasheet.)
5	TDO/TRACESWO	PB5	-	
4	TDI	PB4	-	
-	PA7	XIN32	-	See footnote (2) below
-	PA8	XOUT32	-	See footnote (=/ pelow
-	PB9	XIN	-	See footnote (3) below
-	PB8	XOUT	-	See loothote of below

- Notes: 1. If PB12 is used as PIO input in user applications, a low level must be ensured at startup to prevent Flash erase before the user application sets PB12 into PIO mode,
 - 2. In the product Datasheet Refer to: Slow Clock Generator of the Supply Controller section.
 - 3. In the product Datasheet Refer to: 3 to 20 MHZ Crystal Oscillator information in PMC section.

6.2.1 Serial Wire JTAG Debug Port (SWJ-DP) Pins

The SWJ-DP pins are TCK/SWCLK, TMS/SWDIO, TDO/SWO, TDI and commonly provided on a standard 20-pin JTAG connector defined by ARM. For more details about voltage reference and reset state, refer to Table 3-1 on page 6.

At startup, SWJ-DP pins are configured in SWJ-DP mode to allow connection with debugging probe. Please refer to the Debug and Test Section of the product datasheet.

SWJ-DP pins can be used as standard I/Os to provide users more general input/output pins when the debug port is not needed in the end application. Mode selection between SWJ-DP mode (System IO mode) and general IO mode is performed through the AHB Matrix Special Function Registers (MATRIX SFR). Configuration of the pad for pull-up, triggers, debouncing and glitch filters is possible regardless of the mode.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. It integrates a permanent pull-down resistor of about 15 k Ω to GND, so that it can be left unconnected for normal operations.

By default, the JTAG Debug Port is active. If the debugger host wants to switch to the Serial Wire Debug Port, it must provide a dedicated JTAG sequence on TMS/SWDIO and TCK/SWCLK which disables the JTAG-DP and enables the SW-DP. When the Serial Wire Debug Port is active, TDO/TRACESWO can be used for trace.

The asynchronous TRACE output (TRACESWO) is multiplexed with TDO. So the asynchronous trace can only be used with SW-DP, not JTAG-DP. For more information about SW-DP and JTAG-DP switching, please refer to the Debug and Test Section.

